

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10755042			
<b>Filing Date:</b>	09-Jan-2004			
<b>Title of Invention:</b>	Integrated chip package structure using silicon substrate and method of manufacturing the same			
<b>First Named Inventor/Applicant Name:</b>	Mou-Shiung Lin			
<b>Filer:</b>	Dennis Alan Duchene/Lynne Craig			
<b>Attorney Docket Number:</b>	085027-0104			
Filed as Large Entity				
<b>Utility under 35 USC 111(a) Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>810</b>